

General Description:

The LWT1H70AD3D uses advanced SGT technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications. The package form is PDFN3.3*3.3-8L, which accords with the ROHS standard and Halogen Free standard.

Features:

- Fast Switching
- Low Gate Charge and $R_{DS(ON)}$
- Low Reverse transfer capacitances

Applications:

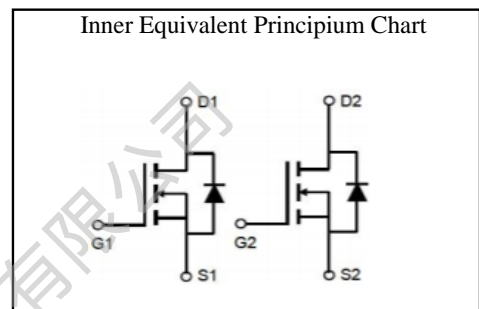
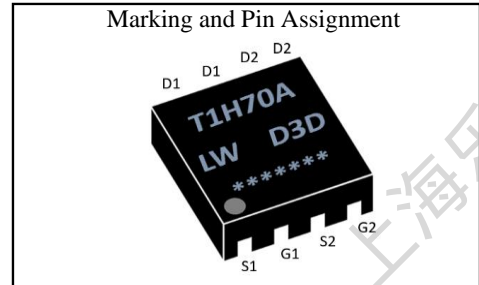
- Battery switching application
- Hard switched and high frequency circuits
- Power Management

100% DVDS Tested

100% Avalanche Tested



V_{DSS}	100	V
I_D	15	A
P_D	31	W
$R_{DS(ON)}$ TYPE	60	m Ω



Package Marking and Ordering Information:

Marking	Part Number	Package	Packing	Qty.
T1H70A/LW D3D/D.C.	LWT1H70AD3D	PDFN3.3*3.3-8L	Reel	5000 Pcs

Absolute Maximum Ratings:

Symbol	Parameter	Value	Units
V_{DSS}	Drain-to-Source Voltage	100	V
I_D	Continuous Drain Current	$T_C=25^\circ\text{C}$	15
	Continuous Drain Current	$T_C=100^\circ\text{C}$	10
I_{DM}^{a1}	Pulsed Drain Current	60	A
E_{AS}^{a2}	Single pulse avalanche energy	22	mJ
V_{GS}	Gate-to-Source Voltage	± 20	V
P_D	Power Dissipation	31	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	150, -55 to 150	$^\circ\text{C}$
T_L	Maximum Temperature for Soldering	260	$^\circ\text{C}$

Thermal Characteristics:

Symbol	Parameter	Value	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	4	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	52	$^\circ\text{C}/\text{W}$

Electrical Characteristic ($T_C = 25\text{ }^\circ\text{C}$, unless otherwise specified):

Static Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
V_{DSS}	Drain to Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	100	--	--	V
I_{DSS}	Drain to Source Leakage Current	$V_{DS}=100V, V_{GS}=0V$	--	--	1.0	μA
$I_{GSS(F)}$	Gate to Source Forward Leakage	$V_{GS}=+20V, V_{DS}=0V$	--	--	100	nA
$I_{GSS(R)}$	Gate to Source Reverse Leakage	$V_{GS}=-20V, V_{DS}=0V$	--	--	-100	nA
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.3	1.8	2.3	V
$R_{DS(ON)1}$	Drain-to-Source On-Resistance	$V_{GS}=10V, I_D=5.0A$	--	60	75	m Ω
$R_{DS(ON)2}$	Drain-to-Source On-Resistance	$V_{GS}=4.5V, I_D=4.A$	--	80	95	m Ω

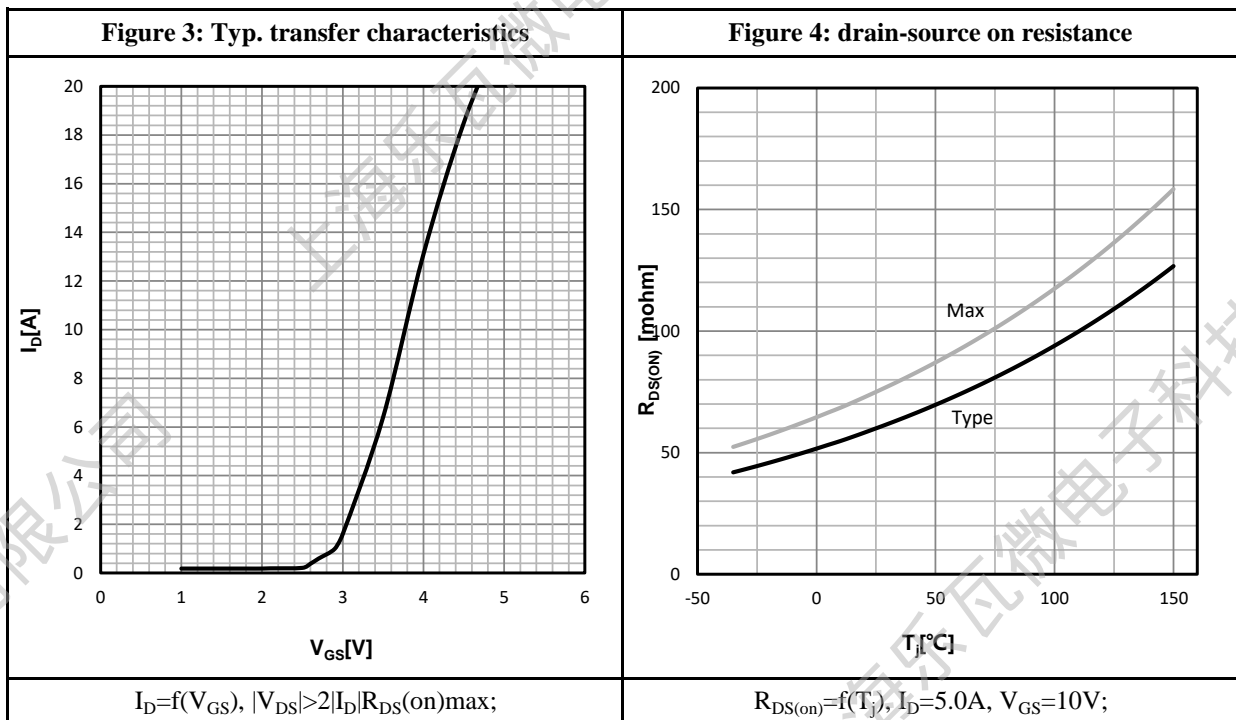
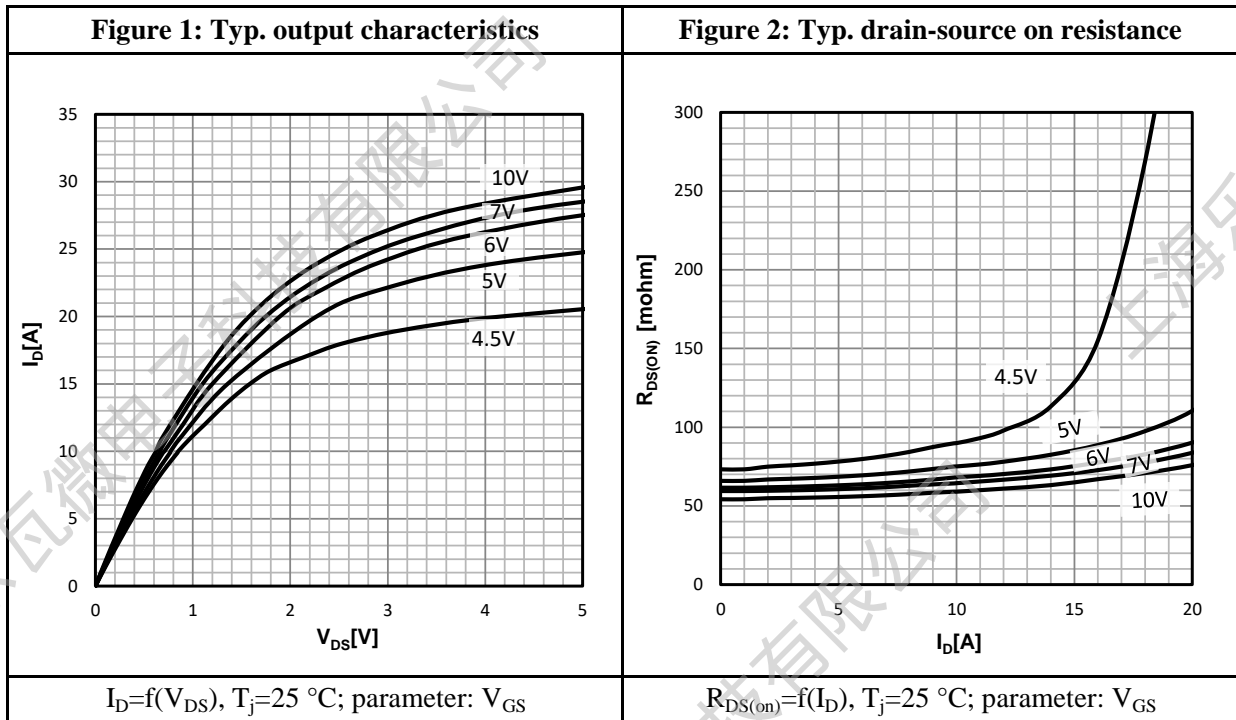
Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
C_{iss}	Input Capacitance	$V_{GS} = 0V$	--	171	--	pF
C_{oss}	Output Capacitance	$V_{DS} = 50V$	--	58	--	
C_{rss}	Reverse Transfer Capacitance	$f = 1.0MHz$	--	1.9	--	

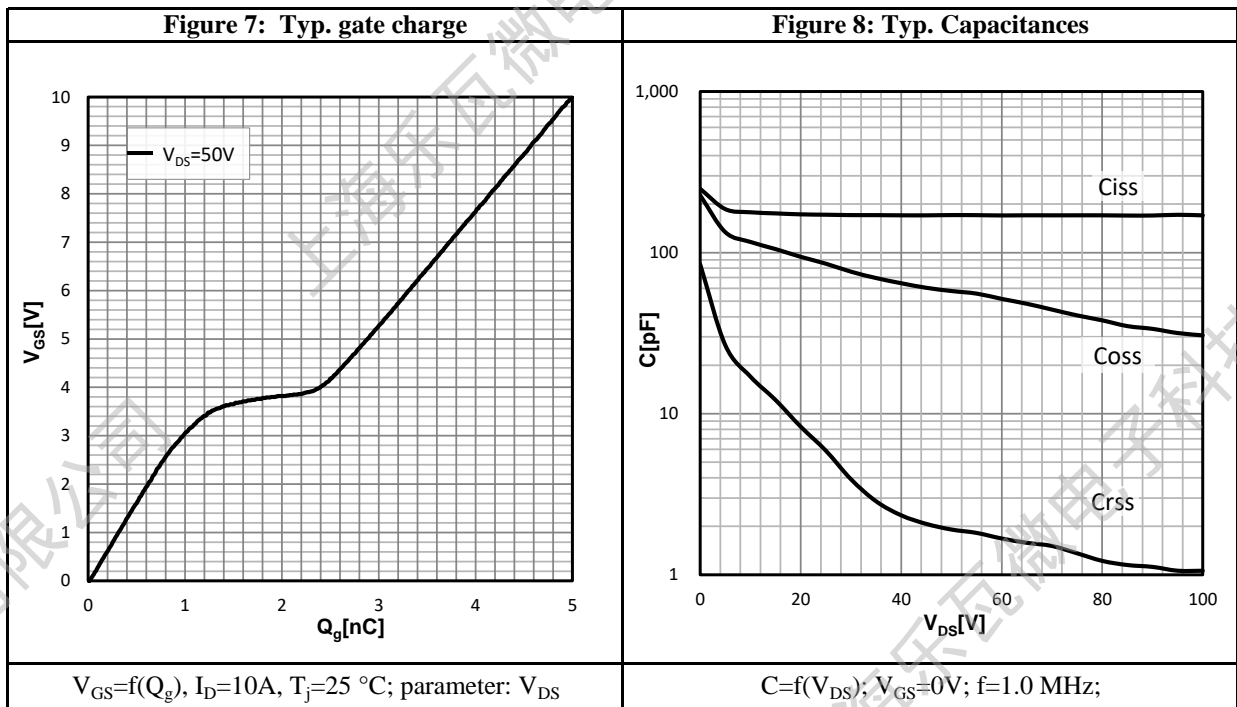
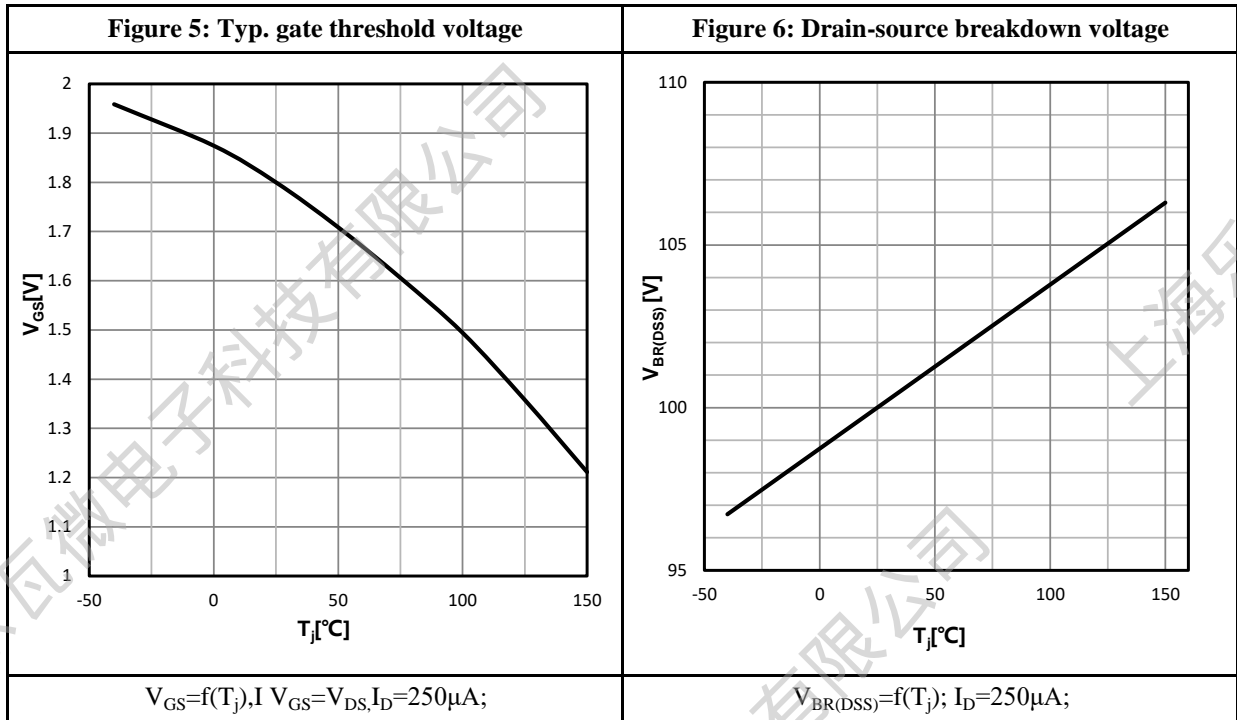
Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
$t_{d(ON)}$	Turn-on Delay Time	$I_D = 10A$ $V_{DS} = 50V$ $V_{GS} = 10V$ $R_G = 3.0\Omega$	--	8	--	ns
t_r	Rise Time		--	16	--	
$t_{d(OFF)}$	Turn-Off Delay Time		--	17	--	
t_f	Fall Time		--	14	--	
Q_g	Total Gate Charge	$V_{GS} = 10V$	--	5.0	--	nC
Q_{gs}	Gate Source Charge	$V_{DS} = 50V$	--	0.8	--	
Q_{gd}	Gate Drain Charge	$I_D = 10A$	--	1.0	--	

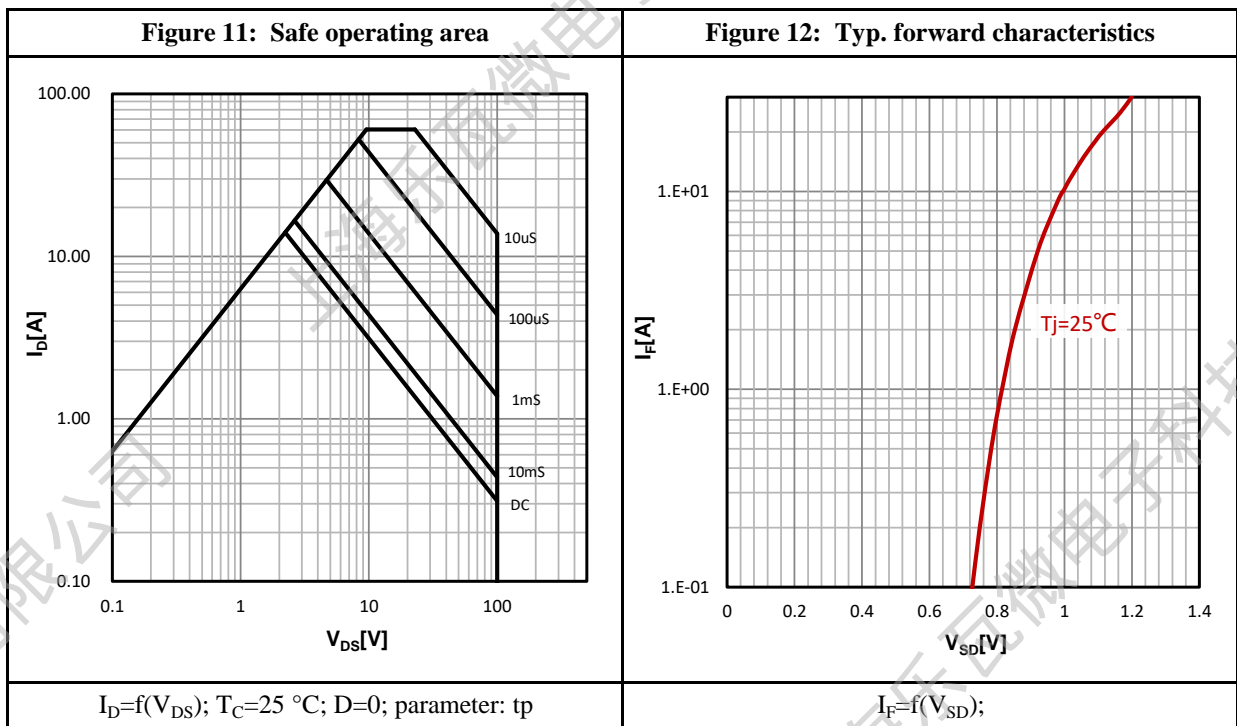
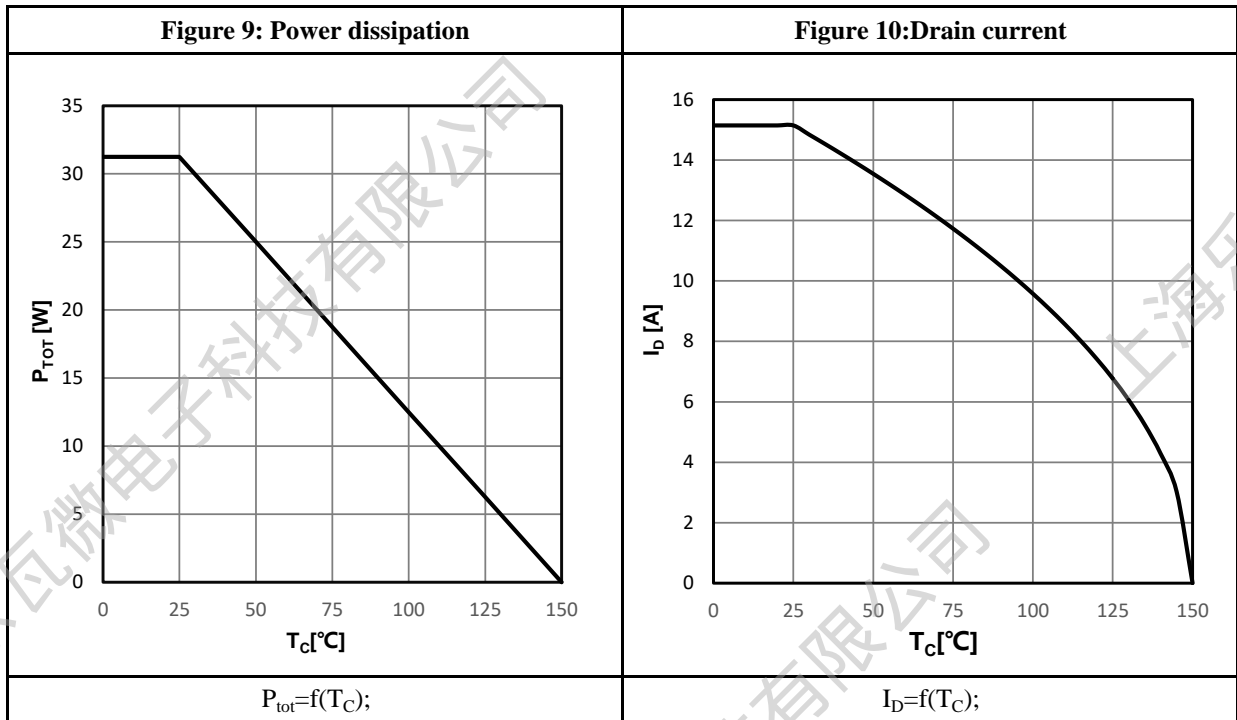
Source-Drain Diode Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
I_S	Diode Forward Current	$T_C = 25\text{ }^\circ\text{C}$	--	--	15	A
V_{SD}	Diode Forward Voltage	$I_S=5.0A, V_{GS}=0V$	--	--	1.2	V
t_{rr}	Reverse Recovery time	$I_S=10A, V_{DD}=50V$	--	22	--	ns
Q_{rr}	Reverse Recovery Charge	$dI/dt=100A/\mu s$	--	18	--	nC

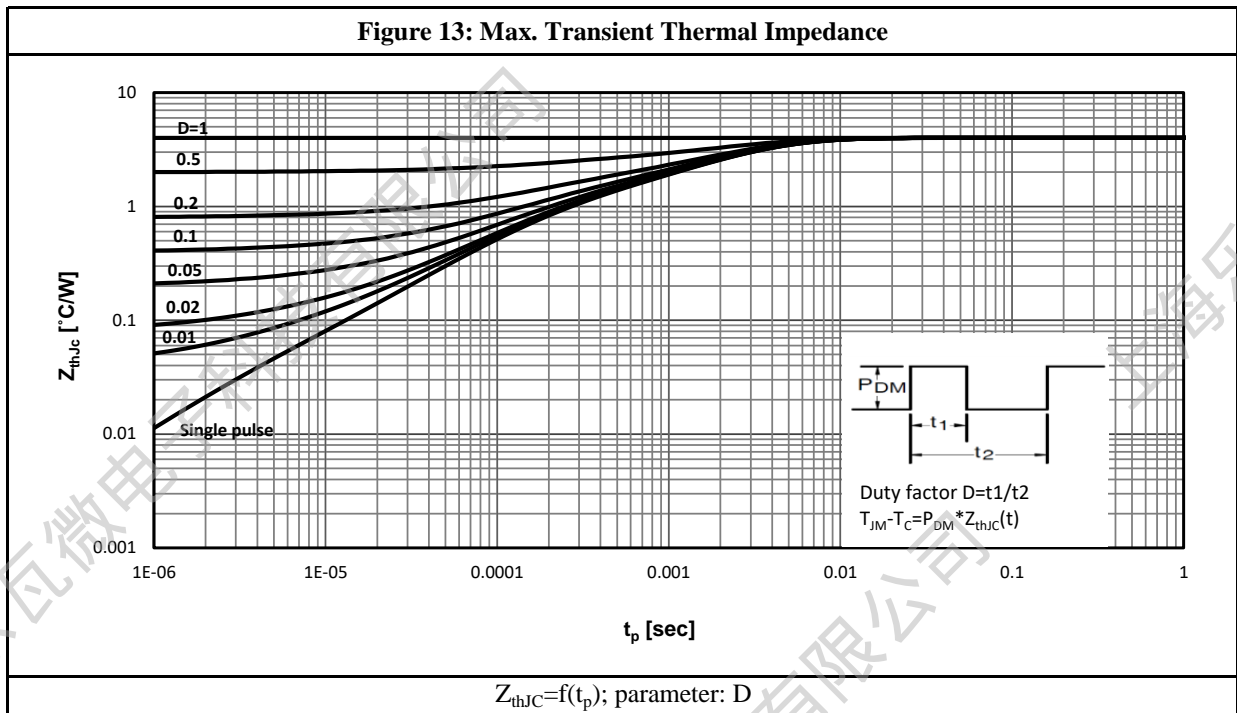
a1: Repetitive rating; pulse width limited by maximum junction temperature

a2: $V_{DD}=50V, L=5.0mH, R_G=25\Omega$, Starting $T_J=25\text{ }^\circ\text{C}$

Characteristics Curve:








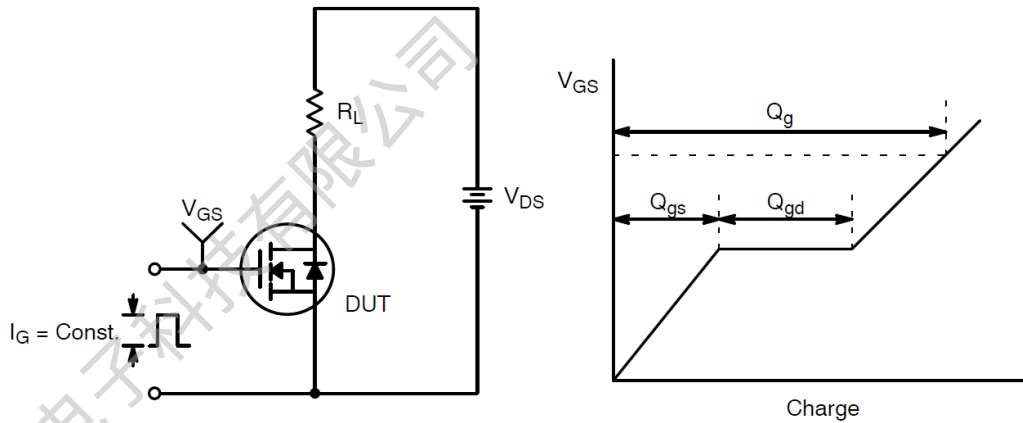
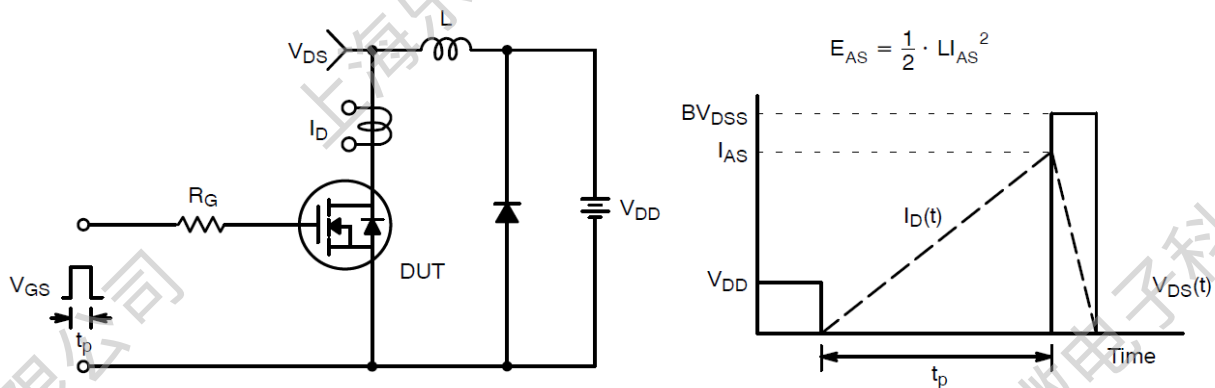
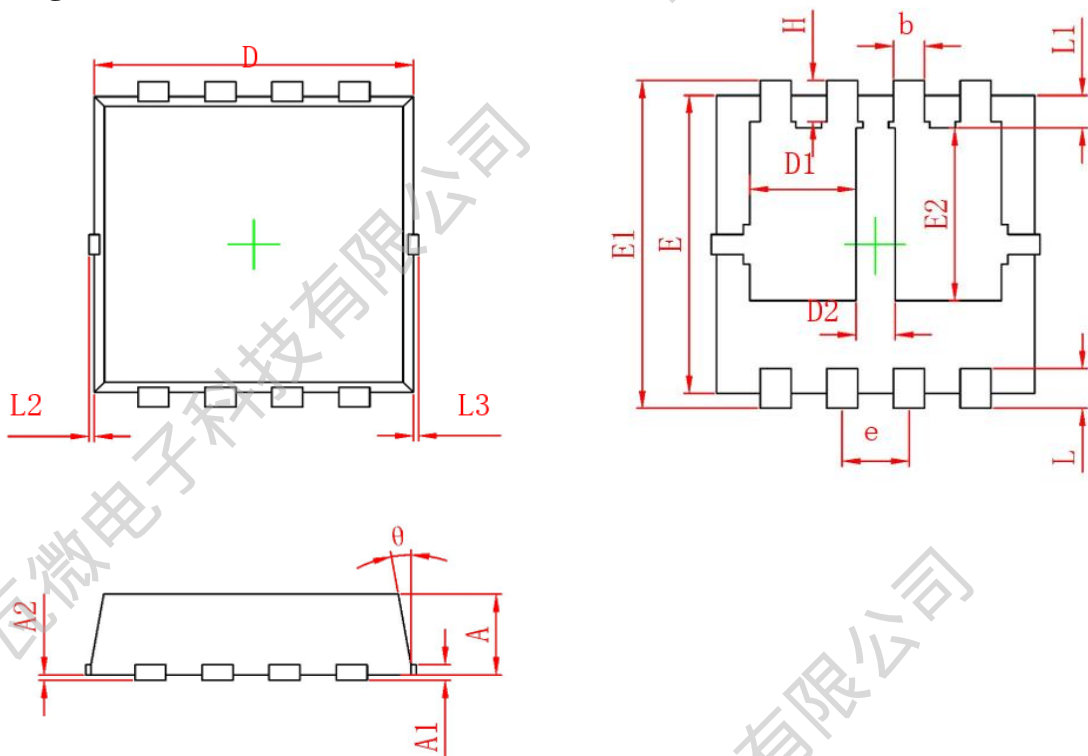
Test Circuit & Waveform:

Figure 14: Gate Charge Test Circuit & Waveform

Figure 15: Resistive Switching Test Circuit & Waveforms

Figure 16: Unclamped Inductive Switching Test Circuit & Waveforms

Package Outline:


Symbol	MILLIMETER	
	MIN	MIN
A	0.700	0.900
A1	0.152 REF	
A2	0~0.05	
D	3.000	3.200
D1	0.935	1.135
D2	0.280	0.480
E	2.900	3.100
E1	3.150	3.450
E2	1.535	1.935
b	0.200	0.400
e	0.550	0.750
L	0.300	0.500
L1	0.180	0.480
L2	0~0.100	
L3	0~0.100	
H	0.315	0.515
θ	8°	12°

Revision History:

Revison	Date	Descriptions
Rev 1.0	Feb.2024	Initial Version

Disclaimer:

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